E·X Renesas Electronics America Inc - <u>UPD78F1142AGK-GAJ-AX Datasheet</u>



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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	78K/0R
Core Size	16-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f1142agk-gaj-ax

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CHAPTER 4 PORT FUNCTIONS

4.1 Port Functions

There are three types of pin I/O buffer power supplies: AVREF, EVDD, and VDD. The relationship between these power supplies and the pins is shown below.

Power Supply	Corresponding Pins
AVREF	P20 to P27
EVdd	 Port pins other than P20 to P27 and P121 to P124 RESET pin and FLMD0 pin
Vdd	P121 to P124 Pins other than port pins (except RESET pin and FLMD0 pin)

Table 4-1. Pin I/O Buffer Power Sup

78K0R/KE3 products are provided with the ports shown in Figure 4-1, which enable variety of control operations. The functions of each port are shown in Table 4-2.

In addition to the function as digital I/O ports, these ports have several alternate functions. For details of the alternate functions, see **CHAPTER 2 PIN FUNCTIONS**.



Figure 4-1. Port Types





- P2: Port register 2
- PM2: Port mode register 2

RD: Read signal

WR××: Write signal

Table 5-4. CPU Clock Transition and SFR Register Setting Examples (3/4)

(6) CPU clock changing from high-speed system clock (C) to internal high-speed oscillation clock (B)

(Setting sequence of SFR registers)				
Setting Flag of SFR Register	CSC Register	Oscillation accuracy	CKC Register	
Status Transition	HIOSTOP	stabilization time	MCM0	
$(C) \rightarrow (B)$	0	10 <i>μ</i> s	0	
		1		



(7) CPU clock changing from high-speed system clock (C) to subsystem clock (D)

(Sett	ing sequence of SFR registers)				
	Setting Flag of SFR Register	CMC Register ^{Note}	CSC Register	Waiting for	CKC Register
Status Transition		OSCSELS	XTSTOP	Oscillation Stabilization	CSS
$(C) \to (D)$		1	0	Necessary	1
				,	

Unnecessary if the CPU is operating with the subsystem clock

Note The CMC register can be written only once by an 8-bit memory manipulation instruction after reset release.

(8) CPU clock changing from subsystem clock (D) to internal high-speed oscillation clock (B)

(Setting sequence of SFR registers)

Setting Flag of SFR Register	CSC Register	CKC R	legister
Status Transition	HIOSTOP	MCM0	CSS
$(D) \rightarrow (B)$	0	0	0
	((

Unnecessary if the CPU I is operating with the re internal high-speed oscillation clock

Unnecessary if this register is already set

Remark (A) to (I) in Table 5-4 correspond to (A) to (I) in Figure 5-15.

Caution When TOE0n = 1, even if the output by timer interrupt of each timer (INTTM0n) contends with writing to TO0n, output is normally done to TO0n pin.

Remark n = 0 to 6

6.4.5 Timer Interrupt and TO0n Pin Output at Operation Start

In the interval timer mode or capture mode, the MD0n0 bit in the TMR0n register sets whether or not to generate a timer interrupt at count start.

When MD0n0 is set to 1, the count operation start timing can be known by the timer interrupt (INTTM0n) generation.

In the other modes, neither timer interrupt at count operation start nor TO0n output is controlled.

Figures 6-32 and 6-33 show operation examples when the interval timer mode (TOE0n = 1, TOM0n = 0) is set.



Figure 6-32. When MD0n0 is set to 1

When MD0n0 is set to 1, a timer interrupt (INTTM0n) is output at count operation start, and TO0n performs a toggle operation.

Figure 6-33. When MD0n0 is set to 0



When MD0n0 is set to 0, a timer interrupt (INTTM0n) is not output at count operation start, and TO0n does not change either. After counting one cycle, INTTM0n is output and TO0n performs a toggle operation.

Remark n = 0 to 6



Figure 6-49. Example of Set Contents of Registers to Measure Input Pulse Interval

(11) Month count register (MONTH)

The MONTH register is an 8-bit register that takes a value of 1 to 12 (decimal) and indicates the count value of months.

It counts up when the day counter overflows.

When data is written to this register, it is written to a buffer and then to the counter up to 2 clocks (32.768 kHz) later. Even if the day count register overflows while this register is being written, this register ignores the overflow and is set to the value written. Set a decimal value of 01 to 12 to this register in BCD code. If a value outside the range is set, the register value returns to the normal value after 1 period.

MONTH can be set by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 01H.

Figure 7-12. Format of Month Count Register (MONTH)

Address: FFF97H After reset: 01H R/W

Symbol	7	6	5	4	3	2	1	0
MONTH	0	0	0	MONTH10	MONTH8	MONTH4	MONTH2	MONTH1

(12) Year count register (YEAR)

The YEAR register is an 8-bit register that takes a value of 0 to 99 (decimal) and indicates the count value of years.

It counts up when the month counter overflows.

Values 00, 04, 08, ..., 92, and 96 indicate a leap year.

When data is written to this register, it is written to a buffer and then to the counter up to 2 clocks (32.768 kHz) later. Even if the month count register overflows while this register is being written, this register ignores the overflow and is set to the value written. Set a decimal value of 00 to 99 to this register in BCD code. If a value outside the range is set, the register value returns to the normal value after 1 period.

YEAR can be set by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 7-13. Format of Year Count Register (YEAR)

Address: FFF98H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
YEAR	YEAR80	YEAR40	YEAR20	YEAR10	YEAR8	YEAR4	YEAR2	YEAR1

(2) Port mode register 14 (PM14)

This register sets port 14 input/output in 1-bit units. When using the P140/INTP6/PCLBUZ0 and P141/INTP7/PCLBUZ1 pins for clock output/buzzer output, clear PM140 and PM141 and the output latches of P140 and P141 to 0. PM14 is set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation sets this register to FFH.

Figure 9-3. Format of Port Mode Register 14 (PM14)



PM14n	P14n pin I/O mode selection (n = 0, 1)
0	Output mode (output buffer on)
1	Input mode (output buffer off)

9.4 Operations of Clock Output/Buzzer Output Controller

One pin can be used to output a clock or buzzer sound.

Two output pins, PCLBUZ0 and PCLBUZ1, are available.

PCLBUZ0 outputs a clock/buzzer selected by clock output select register 0 (CKS0).

PCLBUZ1 outputs a clock/buzzer selected by clock output select register 1 (CKS1).

9.4.1 Operation as output pin

PCLBUZn is output as the following procedure.

- <1> Select the output frequency with bits 0 to 3 (CCSn0 to CCSn2, CSELn) of the clock output select register (CKSn) of the PCLBUZn pin (output in disabled status).
- <2> Set bit 7 (PCLOEn) of CKSn to 1 to enable clock/buzzer output.
- <R> Remarks 1. The controller used for outputting the clock starts or stops outputting the clock one clock after enabling or disabling clock output (PCLOEn) is switched. At this time, pulses with a narrow width are not output. Figure 9-4 shows enabling or stopping output using PCLOEn and the timing of outputting the clock.
 - **2.** n = 0, 1

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Figure 9-4. Remote Control Output Application Example



11.5.2 Master reception

Master reception is that the 78K0R/KE3 outputs a transfer clock and receives data from other device.

	3-Wire Serial I/O	CSI00	CSI10			
	Target channel	Channel 0 of SAU0	Channel 2 of SAU0			
	Pins used	SCK00, SI00	SCK10, SI10			
	Interrupt	INTCSI00	INTCSI10			
<r></r>		Transfer end interrupt (in single-transfer mode) or buffer empty interrupt (in continuous transfer mode) can be selected.				
	Transfer data length	7 or 8 bits				
	Transfer rate	Max. fclk/4 [Hz], Min. fclk/(2 × 2 ¹¹ × 128) [Hz] ^{Note} fclk: System clock frequency				
	Data phase	 Selectable by DAP0n bit DAP0n = 0: Data input starts from the start of the operation of the serial clock. DAP0n = 1: Data input starts half a clock before the start of the serial clock operation. 				
	Clock phase					
	Data direction	MSB or LSB first				

Note Use this operation within a range that satisfies the conditions above and the AC characteristics in the electrical specifications (see CHAPTER 27 ELECTRICAL SPECIFICATIONS (STANDARD PRODUCTS) and CHAPTER 28 ELECTRICAL SPECIFICATIONS ((A) GRADE PRODUCTS)).

Remark n: Channel number (n = 0, 2)

11.7.3 Data reception

Data reception is an operation to receive data to the target for transfer (slave) after transmission of an address field. After all data are received to the slave, a stop condition is generated and the bus is released.

Simplified I ² C	IIC10
Target channel	Channel 2 of SAU0
Pins used	SCL10, SDA10 ^{Note}
Interrupt	INTIIC10
	Transfer end interrupt only (Setting the buffer empty interrupt is prohibited.)
Error detection flag	Overrun error detection flag (OVF02) only
Transfer data length	8 bits
Transfer rate	Max. fmck/4 [Hz] (SDR02[15:9] = 1 or more) fmck: Operation clock (MCK) frequency of target channel However, the following condition must be satisfied in each mode of I ² C. • Max. 400 kHz (first mode) • Max. 100 kHz (standard mode)
Data level	Forward output (default: high level)
Parity bit	No parity bit
Stop bit	Appending 1 bit (ACK transmission)
Data direction	MSB first

Note To perform communication via simplified I²C, set the N-ch open-drain output (V_{DD} tolerance) mode (POM03 = 1) for the port output mode registers (POM0) (see **4.3 Registers Controlling Port Function** for details). When communicating with an external device with a different potential, set the N-ch open-drain output (V_{DD} tolerance) mode (POM04 = 1) also for the clock input/output pins (SCL10) (see **4.4.4 Connecting to external device with different potential (2.5 V, 3 V)** for details).

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The main processing of the slave operation is explained next.

Start serial interface IIC0 and wait until communication is enabled. When communication is enabled, execute communication by using the communication mode flag and ready flag (processing of the stop condition and start condition is performed by an interrupt. Here, check the status by using the flags).

The transmission operation is repeated until the master no longer returns ACK. If ACK is not returned from the master, communication is completed.

For reception, the necessary amount of data is received. When communication is completed, \overline{ACK} is not returned as the next data. After that, the master generates a stop condition or restart condition. Exit from the communication status occurs in this way.





Remark Conform to the specifications of the product that is in communication, regarding the transmission and reception formats.

(2) DMA RAM address register n (DRAn)

This is a 16-bit register that is used to set a RAM address that is the transfer source or destination of DMA channel n.

Addresses of the internal RAM area other than the general-purpose registers (FEF00H to FFEDFH in the case of the μ PD78F1142 and 78F1142A) can be set to this register.

Set the lower 16 bits of the RAM address.

This register is automatically incremented when DMA transfer has been started. It is incremented by +1 in the 8-bit transfer mode and by +2 in the 16-bit transfer mode. DMA transfer is started from the address set to this DRAn register. When the data of the last address has been transferred, DRAn stops with the value of the last address +1 in the 8-bit transfer mode, and the last address +2 in the 16-bit transfer mode.

In the 16-bit transfer mode, the least significant bit is ignored and is treated as an even address.

DRAn can be read or written in 8-bit or 16-bit units. However, it cannot be written during DMA transfer. Reset signal generation clears this register to 0000H.

Figure 14-2. Format of DMA RAM Address Register n (DRAn)

Address: FFFB2H, FFFB3H (DRA0), FFFB4H, FFFB5H (DRA1) After reset: 0000H R/W DRA0H: FFFB3H DRA0L: FFFB2H DRA1H: FFFB5H DRA1L: FFFB4H 14 13 12 10 9 8 7 6 5 4 3 2 15 11 1 0 DRAn (n = 0, 1)

Remark n: DMA channel number (n = 0, 1)

(3) Priority specification flag registers (PR00L, PR00H, PR01L, PR01H, PR02L, PR02H, PR10L, PR10H, PR11L, PR11H, PR12L, PR12H)

The priority specification flag registers are used to set the corresponding maskable interrupt priority level. A priority level is set by using the PR0xy and PR1xy registers in combination (xy = 0L, 0H, 1L, 1H, 2L, or 2H). PR00L, PR00H, PR01L, PR01H, PR02L, PR02H, PR10L, PR10H, PR11L, PR11H, PR12L, and PR12H can be set by a 1-bit or 8-bit memory manipulation instruction. If PR00L and PR00H, PR01L and PR01H, PR02L and PR02H, PR10L and PR10H, PR11L and PR11H, and PR12L and PR12H are combined to form 16-bit registers PR00, PR01, PR02, PR10, PR11, and PR12, they can be set by a 16-bit memory manipulation instruction. Reset signal generation sets these registers to FFH.

Remark If an instruction that writes data to this register is executed, the number of instruction execution clocks increases by 2 clocks.

Figure 15-4. Format of Priority Specification Flag Registers (PR00L, PR00H, PR01L, PR01H, PR02L, PR02H, PR10L, PR10H, PR11L, PR11H, PR12L, PR12H) (1/2)

Address: FFI	FE8H After	reset: FFH	R/W						
Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>	
PR00L	PPR05	PPR04	PPR03	PPR02	PPR01	PPR00	LVIPR0	WDTIPR0	
Address: FFI	FECH After	reset: FFH	R/W						
Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>	
PR10L	PPR15	PPR14	PPR13	PPR12	PPR11	PPR10	LVIPR1	WDTIPR1	
Address: FFFE9H After reset: FFH R/W									
Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>	
PR00H	SREPR00	SRPR00	STPR00	DMAPR01	DMAPR00	SREPR03	SRPR03	STPR03	
		L	CSIPR000						
<u> </u>									
Address: FFI	-EDH After	reset: FFH	R/W						
Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>	
PR10H	SREPR10	SRPR10	STPR10	DMAPR11	DMAPR10	SREPR13	SRPR13	STPR13	
		<u> </u>	CSIPR100	<u> </u>					
Address: FFI	FEAH After	reset: FFH	R/W						
Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>	
PR01L	TMPR003	TMPR002	TMPR001	TMPR000	IICPR00	SREPR01	SRPR01	STPR01	
			1	, ,		1 1		CSIPB010	
					ļ				
								IICPR010	
Address: FE	EEH After	rocat: EEH						IICPR010	
Address: FFF	FEEH After	reset: FFH	R/W		-22	-25	-1	IICPR010	
Address: FFf Symbol	FEEH After <7>	reset: FFH <6>	R/W <5>	<4>	<3>	<2>	<1>	<0>	

IICPR110

	Hardware	Status After Reset Acknowledgment ^{Note 1}
Real-time counter	Subcount register (RSUBC)	0000H
	Second count register (SEC)	00H
	Minute count register (MIN)	00H
	Hour count register (HOUR)	12H
	Day count register (DAY)	01H
	Week count register (WEEK)	00H
	Month count register (MONTH)	01H
	Year count register (YEAR)	00H
	Watch error correction register (SUBCUD)	00H
	Alarm minute register (ALARMWM)	00H
	Alarm hour register (ALARMWH)	12H
	Alarm week register ALARMWW)	00H
	Real-time counter control register 0 (RTCC0)	00H
	Real-time counter control register 1 (RTCC1)	00H
	Real-time counter control register 2 (RTCC2)	00H
Clock output/buzzer output controller	Clock output select registers 0, 1 (CKS0, CKS1)	00H
Watchdog timer	Enable register (WDTE)	1AH/9AH ^{Note 2}
A/D converter	10-bit A/D conversion result register (ADCR)	0000H
	8-bit A/D conversion result register (ADCRH)	00H
	Mode register (ADM)	00H
	Analog input channel specification register (ADS)	00H
	A/D port configuration register (ADPC)	10H
Serial array unit (SAU)	Serial data registers 00, 01, 02, 03, 12, 13 (SDR00, SDR01, SDR02, SDR03, SDR12, SDR13)	0000H
	Serial status registers 00, 01, 02, 03, 12, 13 (SSR00, SSR01, SSR02, SSR03, SSR12, SSR13)	0000H
	Serial flag clear trigger registers 00, 01, 02, 03, 12, 13 (SIR00, SIR01, SIR02, SIR03, SIR12, SIR13)	0000H
	Serial mode registers 00, 01, 02, 03, 12, 13 (SMR00, SMR01, SMR02, SMR03, SMR12, SMR13)	0020H
	Serial communication operation setting registers 00, 01, 02, 03, 12, 13 (SCR00, SCR01, SCR02, SCR03, SCR12, SCR13)	0087H
	Serial channel enable status registers 0, 1 (SE0, SE1)	0000H
	Serial channel start registers 0, 1 (SS0, SS1)	0000H
	Serial channel stop registers 0, 1 (ST0, ST1)	0000H
	Serial clock select registers 0, 1 (SPS0, SPS1)	0000H
	Serial output registers 0, 1 (SO0, SO1)	0F0FH
	Serial output enable registers 0, 1 (SOE0, SOE1)	0000H
	Serial output level registers 0, 1 (SOL0, SOL1)	0000H
	Input switch control register (ISC)	00H

Table 18-2.	Hardware	Statuses	After Reset	Acknowledgment	(2/3)
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Notes 1. During reset signal generation or oscillation stabilization time wait, only the PC contents among the hardware statuses become undefined. All other hardware statuses remain unchanged after reset.

2. The reset value of WDTE is determined by the option byte setting.

23.9.2 Flash shield window function

The flash shield window function is provided as one of the security functions for self programming. It disables writing to and erasing areas outside the range specified as a window only during self programming.

The window range can be set by specifying the start and end blocks. The window range can be set or changed during both on-board/off-board programming and self programming.

Writing to and erasing areas outside the window range are disabled during self programming. During on-board/offboard programming, however, areas outside the range specified as a window can be written and erased.

Figure 23-13. Flash Shield Window Setting Example (Target Devices: μPD78F1142, 78F1142A, Start Block: 04H, End Block: 06H)



Caution If the rewrite-prohibited area of the boot cluster 0 overlaps with the flash shield window range, prohibition to rewrite the boot cluster 0 takes priority.

Table 23-11. Relationship Between Flash Shield Window Function Setting/Change Methods and Commands

Programming Conditions	Window Range	Execution Commands			
	Setting/Change Methods	Block Erase	Write		
Self-programming	Specify the starting and ending blocks by the set information library.	Block erasing is enabled only within the window range.	Writing is enabled only within the range of window range.		
On-board/off-board programming	Specify the starting and ending blocks on GUI of dedicated flash memory programmer, etc.	Block erasing is enabled also outside the window range.	Writing is enabled also outside the window range.		

Remark See 23.7 Security Settings to prohibit writing/erasing during on-board/off-board programming.

Standard Products

DC Characteristics (8/10)

$(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, 1.8 \text{ V} \le \text{AV}_{REF} \le \text{V}_{DD}, \text{V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

Parameter	Symbol		(Conditions		MIN.	TYP.	MAX.	Unit
Supply	DD2 ^{Note 1}	HALT	$f_{MX} = 20 \text{ MHz}^{Note 2}$,		Square wave input		1.0	2.7	mA
current		mode	$V_{DD} = 5.0 V$		Resonator connection		1.3	3.0	mA
			$f_{MX} = 20 \text{ MHz}^{Note 2}$,		Square wave input		1.0	2.7	mA
			$V_{DD} = 3.0 V$		Resonator connection		1.3	3.0	mA
			$f_{MX} = 10 \text{ MHz}^{Notes 2, 3}$,	Square wave input		0.52	1.4	mA
			$V_{DD} = 5.0 V$		Resonator connection		0.62	1.5	mA
			$f_{MX} = 10 \text{ MHz}^{Notes 2, 3}$		Square wave input		0.52	1.4	mA
			$V_{\text{DD}} = 3.0 \text{ V}$	Vdd = 3.0 V			0.62	1.5	mA
			$f_{MX} = 5 \text{ MHz}^{\text{Notes 2, 3}},$	Normal current	Square wave input		0.36	0.75	mA
			V _{DD} = 3.0 V mode	mode	Resonator connection		0.41	0.8	mA
				Low consumption	Square wave input		0.22	0.5	mA
				current mode Note 4	Resonator connection		0.27	0.55	mA
			$f_{MX} = 5 \text{ MHz}^{Notes 2, 3},$	Normal current	Square wave input		0.22	0.5	mA
			$V_{DD} = 2.0 V$	DD = 2.0 V mode			0.27	0.55	mA
				Low consumption	Square wave input		0.22	0.5	mA
			current mode Note 4		Resonator connection		0.27	0.55	mA
			$f_{IH} = 8 \text{ MHz}^{Note 5}$		$V_{DD} = 5.0 V$		0.45	1.2	mA
					V _{DD} = 3.0 V		0.45	1.2	mA

Notes 1. Total current flowing into V_{DD}, EV_{DD}, and AV_{REF}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The maximum value include the peripheral operation current. However, not including the current flowing into the A/D converter, LVI circuit, I/O port, and on-chip pull-up/pull-down resistors. During HALT instruction execution by flash memory.

- 2. When internal high-speed oscillator and subsystem clock are stopped.
- 3. When AMPH (bit 0 of clock operation mode control register (CMC)) = 0 and FSEL (bit 0 of operation speed mode control register (OSMC)) = 0.
- 4. When the RMC register is set to 5AH.
- 5. When high-speed system clock and subsystem clock are stopped. When FSEL (bit 0 of operation speed mode control register (OSMC)) = 0 is set.
- Remarks 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 - fin: Internal high-speed oscillation clock frequency
 - 2. For details on the normal current mode and low consumption current mode according to the regulator output voltage, refer to CHAPTER 21 REGULATOR.
 - **3.** Temperature condition of the TYP. value is $T_A = 25^{\circ}C$

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(A) Grade Products

Parameter	Symbols		Conditions	Ratings	Unit
Output current, high Iонт Per pin P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P70 to P77, P120, P130, P14 P141		P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P70 to P77, P120, P130, P140, P141	-10	mA	
		Total of all pins –80 mA	P00 to P04, P40 to P43, P120, P130, P140, P141	-25	mA
			P05, P06, P10 to P17, P30, P31, P50 to P55, P70 to P77	-55	mA
	Іон2	Per pin	P20 to P27	-0.5	mA
		Total of all pins		-2	mA
Output current, low	lol1	Per pin	P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P60 to P63, P70 to P77, P120, P130, P140, P141	30	mA
		Total of all pins 200 mA	P00 to P04, P40 to P43, P120, P130, P140, P141	60	mA
			P05, P06, P10 to P17, P30, P31, P50 to P55, P60 to P63, P70 to P77	140	mA
	IOL2	Per pin	P20 to P27	1	mA
		Total of all pins		5	mA
Operating ambient	Та	In normal operation mode		-40 to +85	°C
temperature		In flash memory	programming mode		
Storage temperature	Tstg			-65 to +150	°C

Absolute Maximum Ratings (T_A = 25°C) (2/2)

- Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- **Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

AC Characteristics

(1) Basic operation (1/6)

$(T_{A} = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, 1.8 \text{ V} \le \text{AV}_{REF} \le \text{V}_{DD}, \text{V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

Parameter	Symbol		Conditions		MIN.	TYP.	MAX.	Unit
Instruction cycle	Тсү	Main system clock	Normal	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	0.05		8	μS
(minimum instruction		(fmain) operation	current mode	$1.8~V \leq V_{\text{DD}} < 2.7~V$	0.2		8	μS
execution time)			Low consump	tion current mode	0.2		8	μs
		Subsystem clock (fsu	в) operation		57.2	61	62.5	μs
		In the self programming mode	Normal current mode	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	0.05		0.5	μS
External main system	fex	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	Normal currer	it mode	2.0		20.0	MHz
clock frequency			Low consump	tion current mode	2.0		5.0	MHz
		$1.8~V \leq V_{\text{DD}} < 2.7~V$			2.0		5.0	MHz
External main system	texh, texl	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	Normal currer	nt mode	24			ns
clock input high-level			Low consumption current mode		96			ns
width, low-level width		$1.8 \text{ V} \leq \text{V}_{\text{DD}} < 2.7 \text{ V}$		96			ns	
TI00 to TI06 input high-level width, low- level width	tтıн, tтı∟				1/fмск + 10			ns
TO00 to TO06 output	fтo	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	$2.7 \text{ V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$				10	MHz
frequency		$1.8~V \leq V_{\text{DD}} < 2.7~V$					5	MHz
PCLBUZ0, PCLBUZ1	fpcl	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$					10	MHz
output frequency		$1.8~V \leq V_{\text{DD}} < 2.7~V$					5	MHz
Interrupt input high- level width, low-level width	tinth, tintl				1			μS
Key interrupt input low-level width	tкв				250			ns
RESET low-level width	trsl				10			μS

Remarks 1. fmck: Timer array unit operation clock frequency

(Operation clock to be set by the CKS0n bit of the TMR0n register. n: Channel number (n = 0 to 6))

2. For details on the normal current mode and low consumption current mode according to the regulator output voltage, refer to CHAPTER 21 REGULATOR.

(A) Grade Products

(2) Serial interface: Serial array unit (12/18)

<R>

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 2.7 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, \text{V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

(f) During Communication at different potential (2.5 V, 3 V) (CSI mode) (master mode, SCK10... internal clock output) (2/2)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
SI10 setup time	tsıĸı	$4.0~V \leq V_{\text{DD}} \leq 5.5~V,~2.7~V \leq V_{\text{b}} \leq 4.0~V,$	70			ns
(to SCK10↓) ^{Note}		$C_{b}=30 \text{ pF}, \text{R}_{b}=1.4 \text{k}\Omega$				
		$2.7~V \leq V_{\text{DD}} \leq 4.0~V,~2.3~V \leq V_{\text{b}} < 2.7~V,$	100			ns
		$C_b=30 \text{ pF}, \text{R}_b=2.7 \text{k}\Omega$				
SI10 hold time	tksi1	$4.0~V \leq V_{\text{DD}} \leq 5.5~V,~2.7~V \leq V_{\text{b}} \leq 4.0~V,$	30			ns
(from $\overline{\text{SCK10}}\downarrow$) ^{Note}		$C_{b}=30 \text{ pF}, \text{R}_{b}=1.4 \text{k}\Omega$				
		$2.7~V \leq V_{\text{DD}} \leq 4.0~V,~2.3~V \leq V_{\text{b}} < 2.7~V,$	30			ns
		$C_{b}=30 \text{ pF}, \text{ R}_{b}=2.7 \text{ k}\Omega$				
Delay time from $\overline{\text{SCK10}}$ to	tkso1	$4.0~V \leq V_{\text{DD}} \leq 5.5~V,~2.7~V \leq V_{b} \leq 4.0~V,$			40	ns
SO10 output Note		$C_{\rm b}=30~pF,~R_{\rm b}=1.4~k\Omega$				
		$\label{eq:VDD} 2.7 \ V \leq V_{\text{DD}} \leq 4.0 \ V, \ 2.3 \ V \leq V_{\text{b}} < 2.7 \ V,$			40	ns
		$C_{b}=30 \text{ pF}, \text{ R}_{b}=2.7 \text{ k}\Omega$				

Note When DAP02 = 0 and CKP02 = 1, or DAP02 = 1 and CKP02 = 0.

CSI mode connection diagram (during communication at different potential)



Caution Select the TTL input buffer for SI10 and the N-ch open drain output (VDD tolerance) mode for SO10 and SCK10 by using the PIM0 and POM0 registers.

Remarks 1. $R_b[\Omega]$:Communication line (SCK10, SO10) pull-up resistance,

Cb[F]: Communication line (SCK10, SO10) load capacitance, Vb[V]: Communication line voltage

2. V_{IH} and V_{IL} below are observation points for the AC characteristics of the serial array unit when communicating at different potentials in CSI mode.

$$4.0 \text{ V} \le V_{\text{DD}} \le 5.5 \text{ V}, 2.7 \text{ V} \le V_{\text{b}} \le 4.0 \text{ V}$$
: VIH = 2.2 V, VIL = 0.8 V

 $2.7~V \leq V_{\text{DD}} \leq 4.0~V,\, 2.3~V \leq V_{\text{b}} \leq 2.7~V;\, V_{\text{IH}} = 2.0~V,\, V_{\text{IL}} = 0.5~V$

3. CSI00 cannot communicate at different potential. Use CSI10 for communication at different potential.

(A) Grade Products

(4) Serial interface: On-chip debug (UART)

(TA = -40 to +85°C, 1.8 V \leq VDD = EVDD \leq 5.5 V, Vss = EVss = AVss = 0 V)

(a) On-chip debug (UART)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate			fськ/2 ¹²		fськ/6	bps
		Flash memory programming mode			2.66	Mbps
TOOL1 output frequency	ftool1	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$			10	MHz
		$1.8 \text{ V} \leq \text{Vdd} < 2.7 \text{ V}$			2.5	MHz

<R> 64-PIN PLASTIC FBGA (6x6)





	(UNIT:mm)
ITEM	DIMENSIONS
D	6.00±0.10
E	6.00±0.10
w	0.20
А	1.41±0.10
A1	0.30±0.05
A2	1.11
е	0.65
b	$0.40 {\pm} 0.05$
x	0.08
У	0.10
y1	0.20
ZD	0.725
ZE	0.725
	P64F1-65-BA4

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